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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A multilayer composite comprising:
an insulating substrate; and
patterned conductive layers and insulating layers alternately laminated on the insulating substrate to define a laminate; wherein
at least one of the insulating layers defines a correcting insulating layer including vitreous silica and quartz; and
the ratio of vitreous silica to quartz in the correcting insulating layer differs from that in the other insulating layers ~~is determined~~ such that the thermal expansion coefficient of the correcting insulating layer differs from that of the insulating layers that do not define the correcting insulating layer, such that the correcting insulating layer corrects the warpage of the laminate attributed to a difference in thermal expansion coefficients between the insulating layers that do not define the correcting insulating layer, the patterned conductive layers, and the insulating substrate.

Claim 2 (original): The multilayer composite according to claim 1, wherein at least a top layer of the laminate is the correcting insulating layer.

Claim 3 (original): The multilayer composite according to claim 1, wherein the patterned conductive layers include a patterned photosensitive conductive paste.

Claim 4 (currently amended): The multilayer composite according to ~~either~~ claim 1, wherein at least one of the insulating layers has a via hole, at least two of the

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patterned conductive layers are connected through said via hole, and said at least one of the insulating layers is made of a patterned photosensitive insulating paste.

Claim 5 (currently amended): The multilayer composite according to either claim 1, wherein each of the insulating layers includes vitreous silica and quartz.

Claim 6 (currently amended): The multilayer composite according to either claim 1, wherein at least one of the insulating layers includes a via hole for connecting two of said patterned conductive layers.

Claim 7 (currently amended): A multilayer composite comprising:
an insulating substrate; and
patterned conductive layers and insulating layers alternately laminated on the insulating substrate so as to define a laminate; wherein
each of the insulating layers includes vitreous silica and quartz;
at least one of the insulating layers defines a correcting insulating layer; and
the ratio of vitreous silica to quartz in the correcting insulating layer differs from that in the other insulating layers such that the thermal expansion coefficient of the correcting insulating layer differs from that of the insulating layers that do not define the correcting insulating layer, such that the correcting insulating layer corrects the warpage of the laminate attributed to a difference in thermal expansion coefficient between the insulating layers that do not define the correcting insulating layer, the patterned conductive layers, and the insulating substrate.

Claim 8 (original): The multilayer composite according to claim 7, wherein at least a top layer of the laminate is the correcting insulating layer.

Claim 9 (original): The multilayer composite according to claim 7, wherein the patterned conductive layers are made of a patterned photosensitive conductive paste.

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Claim 10 (currently amended): The multilayer composite according to either claim 7, wherein at least one of the insulating layers has a via hole, at least two of the patterned conductive layers are connected through said via hole, and said insulating layer is made of a patterned photosensitive insulating paste.

Claim 11 (currently amended): The multilayer composite according to either claim 7, wherein at least one of the insulating layers includes a via hole for connecting two of said patterned conductive layers.

Claims 12-17 (canceled).

Claim 18 (new): The multilayer composite according to claim 1, wherein the at least one of the insulating layers defining the correcting insulating layer includes more vitreous silica than quartz to correct a concave warpage of the laminate.

Claim 19 (new): The multilayer composite according to claim 1, wherein the at least one of the insulating layers defining the correcting insulating layer includes more quartz than vitreous silica to correct a convex warpage of the laminate.

Claim 20 (new): The multilayer composite according to claim 7, wherein the at least one of the insulating layers defining the correcting insulating layer includes more vitreous silica than quartz to correct a concave warpage of the laminate.

Claim 21 (new): The multilayer composite according to claim 7, wherein the at least one of the insulating layers defining the correcting insulating layer includes more quartz than vitreous silica to correct a convex warpage of the laminate.